



2010 IEEE Workshop on Microelectronics and Electron Devices

April 16, 2010

Boise State University – Jordan Ballroom, Boise, Idaho

<http://www.ewh.ieee.org/r6/boise/wmed2010/WMED2010.html>

WMED Highlights:

- Limited number of 'Student Travel Awards'
- WMED-2010 confirmed invited speakers:
Tahir Ghani (Intel), **Peter Hartwell** (HP Labs), **Kaustav Banerjee** (UC-Santa Barbara), **Christopher Wronski** (Penn State), **Todd Marquart** (Micron)
- Best paper and best poster awards

Important Dates:

Manuscript submission: 1/25/2010
Revised manuscript: 2/22/2010
Advance registration: 3/25/2010

International Authors: If you require a US VISA and letter of acknowledgment from WMED in order to attend the workshop and present your paper, we strongly urge that you submit your manuscript early (recommended manuscript submission by 1/4/2010) and request "expedited review".

WMED-2010 Call for Papers

The eighth annual IEEE Workshop on Microelectronics and Electron Devices (WMED) will provide a forum for reviewing and discussing all aspects of micro- and nano-electronics including processing, electrical characterization, design, and new device technologies. This symposium will consist of invited and contributed talks, papers and a poster session throughout the day. Faculty, students, and researchers in industry are encouraged to contribute presentations on either completed research or works in progress. Topics in the following areas will form the contributing sessions and poster session in the workshop program:

• **Microelectronic Device Processing and Process Integration**

Trends in submicron technologies; product development (DRAM, SRAM, Flash, CMOS Imagers); new device technologies (Phase Change Memory, Resistive Memory, Ferroelectric Memory), novel transistors.

• **MEMS and Nanoelectronic Devices**

Novel processes and materials, MEMS research, development and performance; nanotubes, nanowires, quantum dots, molecular devices, device characterization for nanoelectronic devices.

• **Microelectronic Device Electrical and Reliability Testing**

Dielectric reliability; device reliability; phase change memory reliability; novel memory technology testing schemes; electrical properties of novel devices.

• **Semiconductor Packaging and Reliability**

Semiconductor package reliability, Design for Manufacturability, stacked die packaging, and novel assembly processes. Novel packaging structures, processes, materials research, development, and performance.

• **Microelectronic Circuit Design**

New product design, design techniques and memory sensing schemes.

All accepted manuscripts will be indexed in the IEEE Xplore database. A printed proceeding of the accepted papers as well as a CD-ROM including the papers and presentations is planned and will be available at the start of the workshop.

Please submit your IEEE-formatted manuscript (up to 4 pages) by **January 25th, 2010** to the WMED Publications Chair, Prashant Raghu (praghu@micron.com, +1 208-368-2901). Submitted manuscripts must strictly follow the IEEE publication format guidelines. A template containing manuscript preparation instructions can be downloaded at: <http://www.ewh.ieee.org/r6/boise/wmed2010/CFP.html>. The Technical Program Committee will have a peer-review process to meet the IEEE criterion for minimum standards of quality (details on the website). Questions concerning the conference can be directed to: William Kueber (IEEE WMED2010 General Chair, billrk@ieee.org, +1 208-368-3008).

This workshop is receiving technical co-sponsorship support from the IEEE Electron Devices Society.